

What is claimed is:

[Claim 1] 1. A wafer carrier for carrying a wafer, comprising:
a transparent base; and
a conducting layer positioned on a bottom surface of the transparent base.

[Claim 2] 2. The wafer carrier of claim 1, wherein the transparent base has dimensions similar to that of the wafer.

[Claim 3] 3. The wafer carrier of claim 1, wherein the transparent base is a glass wafer.

[Claim 4] 4. The wafer carrier of claim 1, wherein the transparent base is a quartz wafer.

[Claim 5] 5. The wafer carrier of claim 1 further comprising a bonding layer positioned on a top surface of the wafer carrier for bonding the wafer and the transparent base together.

[Claim 6] 6. The wafer carrier of claim 5, wherein the bonding layer is selected from the group consisting of double-sided tape, ultra violet tape, thermal sensitive tape, photo resist, and wax.

[Claim 7] 7. The wafer carrier of claim 1, wherein the wafer carrier is attracted by an electrostatic chuck via the conducting layer so that the wafer is transferred and undergoes at least a semiconductor process.

[Claim 8] 8. The wafer carrier of claim 7, wherein the semiconductor process is a double-sided process, and the wafer comprises at least an alignment mark.

[Claim 9] 9. The wafer carrier of claim 8, wherein the conducting layer is a transparent conducting layer.

[Claim 10] 10. The wafer carrier of claim 8, wherein the conducting layer is a non-transparent conducting layer having at least an exposed region corresponding to the alignment mark.

[Claim 11] 11. The wafer carrier of claim 10, wherein the non-transparent conducting layer comprises a plurality of conducting patterns connected with each other.

[Claim 12] 12. A wafer carrier adapted for use in a double-sided process for carrying a wafer, comprising:

a transparent base;

a conducting layer positioned on a bottom surface of the transparent base;
and

a bonding layer positioned on a top surface of the transparent base for bonding the wafer and the transparent base.

[Claim 13] 13. The wafer carrier of claim 12, wherein the transparent base has dimensions similar to that of the wafer.

[Claim 14] 14. The wafer carrier of claim 12, wherein the transparent base is a glass wafer.

[Claim 15] 15. The wafer carrier of claim 12, wherein the transparent base is a quartz wafer.

[Claim 16] 16. The wafer carrier of claim 12, wherein the bonding layer is selected from the group consisting of double-sided tape, ultra violet tape, thermal sensitive tape, photo resist, and wax.

[Claim 17] 17. The wafer carrier of claim 12, wherein the wafer carrier is attracted by an electrostatic chuck via the conducting layer so that the wafer is transferred and undergoes the double-sided process.

[Claim 18] 18. The wafer carrier of claim 17, wherein the wafer comprises at least an alignment mark.

[Claim 19] 19. The wafer carrier of claim 18, wherein the conducting layer is a transparent conducting layer.

[Claim 20] 20. The wafer carrier of claim 18, wherein the conducting layer is a non-transparent conducting layer having at least an exposed region corresponding to the alignment mark.

[Claim 21] 21. The wafer carrier of claim 12, wherein the non-transparent conducting layer comprises a plurality of conducting patterns connected with each other.